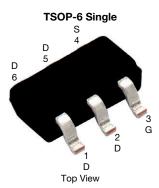
Vishay Siliconix

N-Channel 40 V (D-S) MOSFET



Marking code: AW

PRODUCT SUMMARY						
V _{DS} (V)	40					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0355					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0425					
Q _g typ. (nC)	5.3					
I _D (A) ^a	7.4					
Configuration	Single					

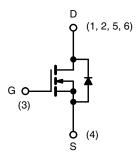
FEATURES

- TrenchFET® power MOSFET
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

• DC/DC Converter



N-Channel MOSFET

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free	Si3438DV-T1-E3
Lead (Pb)-free and halogen-free	Si3438DV-T1-GE3

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	25 °C, unless otherv	vise noted		
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	40	V	
Gate-source voltage		V_{GS}	± 20	V
	T _C = 25 °C		7.4	
Continuous dusin surrent (T. 150 °C)	T _C = 70 °C	. [5.8	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	l _D	5.5 b, c	A
	T _A = 70 °C		4.4 b, c	
Pulsed drain current	I _{DM}	20	1	
Continuous source dusin diada surrent	T _C = 25 °C	I _S	2.9	
Continuous source-drain diode current	T _A = 25 °C		1.6 ^{b, c}	
	T _C = 25 °C		3.5	
Maximum navvar discipation	T _C = 70 °C		2.2	\\\
Maximum power dissipation	T _A = 25 °C	P _D	2 b,c	W
	T _A = 70 °C	1	1.25 ^{b, c}	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b, d	t ≤ 5 s	R _{thJA}	50	62.5	°C/W
Maximum junction-to-foot	Steady state	R _{thJF}	28	35	C/VV

Notes

- a. Based on 25 °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 110 °C/W



Vishay Siliconix

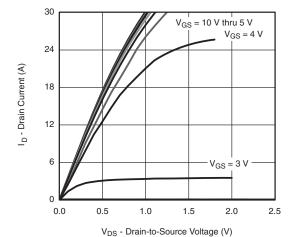
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Static	<u> </u>		· I	l		ı	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	J 250 A	-	44	-	mV/°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$	-	-5.5	-		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.4	-	3	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zava sata valtasa duain avuvant		V _{DS} = 40 V, V _{GS} = 0 V	-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	μA	
On-state drain current a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10	-	-	Α	
Duning and an artists and a	Б	V _{GS} = 10 V, I _D = 5 A	-	0.0295	0.0355		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 4 A	-	0.0355	0.0425	Ω	
Forward transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5 A	-	22	-	S	
Dynamic ^b					•		
Input capacitance	C _{iss}		-	640	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	73	-		
Reverse transfer capacitance	C _{rss}		-	41	-		
Total gate charge	Q _g	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	-	11.7	20	nC	
			-	5.3	9		
Gate-source charge	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$	-	1.9	-		
Gate-drain charge	Q _{gd}		-	1.7	-		
Gate resistance	R_g	f = 1 MHz	0.45	2.2	4.4	Ω	
Turn-on delay time	t _{d(on)}		-	16	30		
Rise time	t _r	V_{DD} = 20 V, R_L = 4 Ω	-	17	35	1	
Turn-off delay time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	16	30		
Fall time	t _f		-	10	20		
Turn-on delay time	t _{d(on)}		-	7	14	ns	
Rise time	t _r	V_{DD} = 20 V, R_L = 4 Ω	-	10	20		
Turn-off delay time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 10 V, R_g = 1 Ω		15	30		
Fall time	t _f		-	9	18		
Drain-Source Body Diode Characteris	tics				•		
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	2.9	^	
Pulse diode forward current	I _{SM}		-	-	20	Α	
Body diode voltage	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V	-	0.78	1.2	V	
Body diode reverse recovery time	t _{rr}	* *	-	19	35	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 3 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$	-	14	30	nC	
Reverse recovery fall time	t _a	T _J = 25 °C	-	13	-		
Reverse recovery rise time	t _b		_	6	_	ns	

Notes

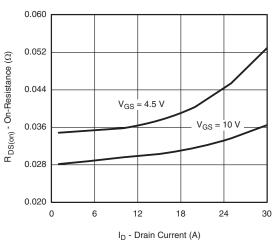
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

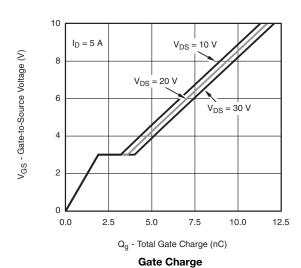


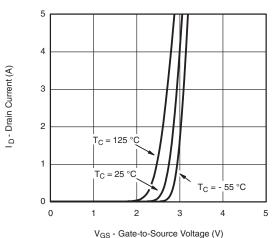


Output Characteristics

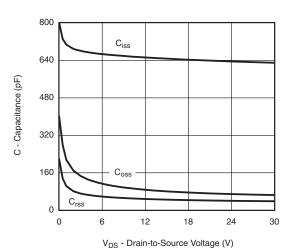


On-Resistance vs. Drain Current and Gate Voltage

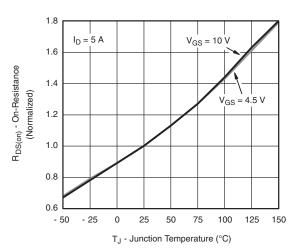




Transfer Characteristics

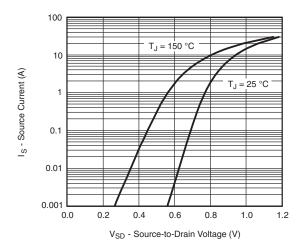


Capacitance

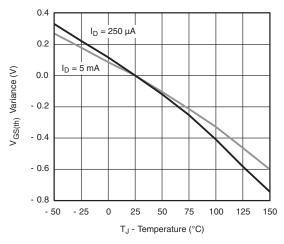


On-Resistance vs. Junction Temperature

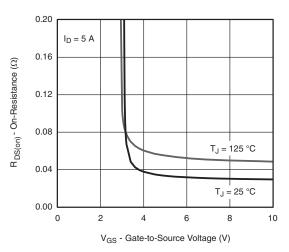




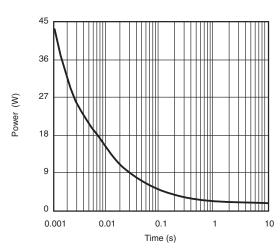
Source-Drain Diode Forward Voltage



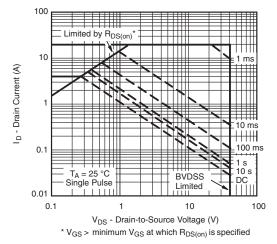
Threshold Voltage



On-Resistance vs. Gate-to-Source Temperature

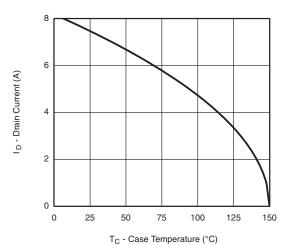


Single Pulse Power, Junction-to-Ambient

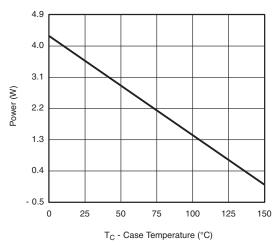


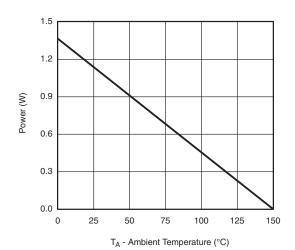
Safe Operating Area, Junction-to-Ambient





Current Derating a





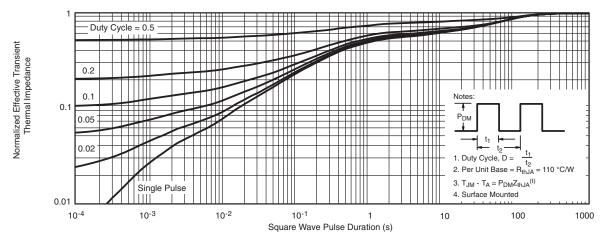
Power Derating, Junction-to-Foot

Power Derating, Junction-to-Ambient

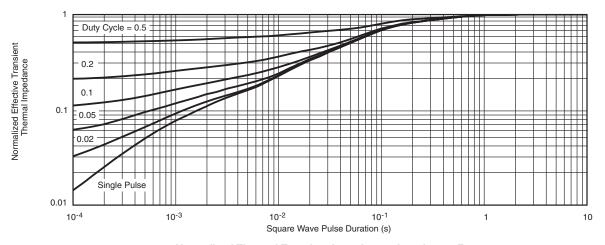
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68393.





TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C





5-LEAD TSOP







	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.008		
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂		0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1	7° Nom			7° Nom			
ECN: C		ev. I, 18-Dec	c-06				

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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